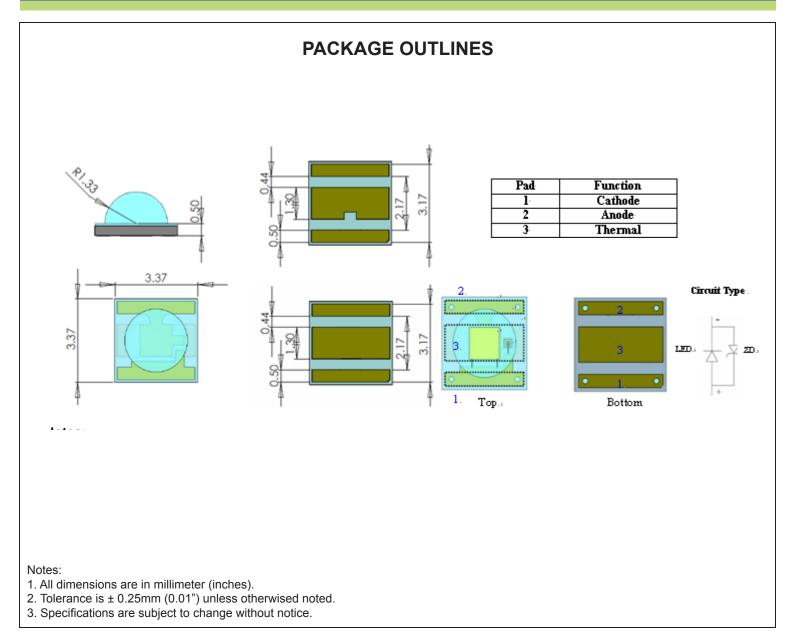


### SPECIFICATIONS





Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CSHU33NW2ZC	InGaN	White	Water Clear	120°





## **ABSOLUTE MAXIMUM RATINGS**

(TA:	=25	°C

Parameter	Symbol	Max Rating	Unit
Forward Current	lf	500	mA
ESD Threshold (HBM)	V	2000	V
Reverse Voltage	V	5	V
Junction Temperature	ТJ	125	°C
Operating Temperature Range	Тор	-40~+100	°C
Storage Temperature Range	Тѕтс	-40~+100	°C
Peak Pulsing Current (1/10 duty f = 10KHz)	IFP	-	mA
Soldering Temperature	Tsol	Max 260°C for 5 sec Max	

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

## (TA=25°C)

Deremeter	Symbol	abol Toot Condition		Value		
Parameter	Symbol Test Condition		Min	Тур	Max	Unit
CCT Range	Х	l⊧ = 350mA	-	0.35	-	-
CCT Range	Y	l⊧ = 350mA	-	0.36	-	-
Reverse Leakage Current	lr	V <sub>R</sub> = 12V	-	-	-	μA
Forward Voltage	VF	l⊧ = 350mA	-	3.4	3.75	V
Luminous Intensity	lv	l⊧ = 350mA	74	80	-	lm

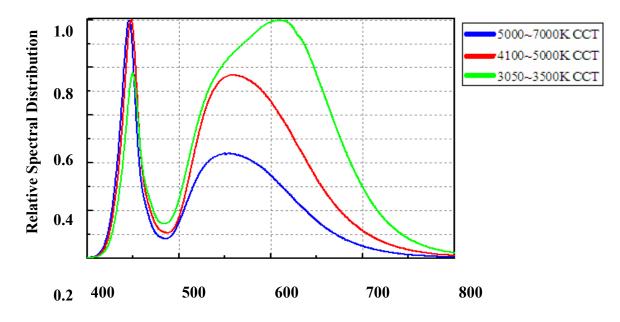
\*Tolerance of viewing angle: -10 / +5 deg.





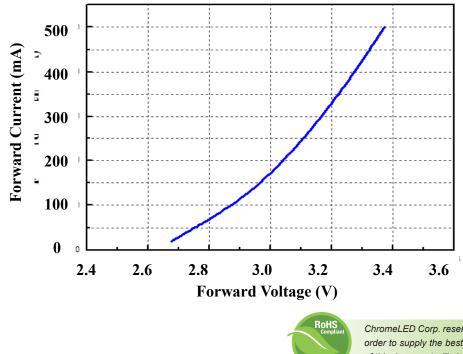
## **RELATIVE SPECTRAL CHARACTERISTICS & ELECTRICAL CHARACTERISTICS**

Relative Spectral Characteristics, Tj=25<sup>o</sup>C, I<sub>F</sub>=350mA



Wavelength (nm)

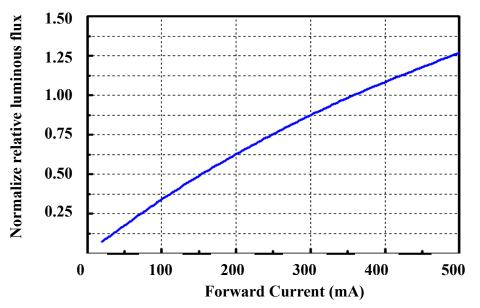
Typical Electrical Characteristics, Tj=25<sup>0</sup>C



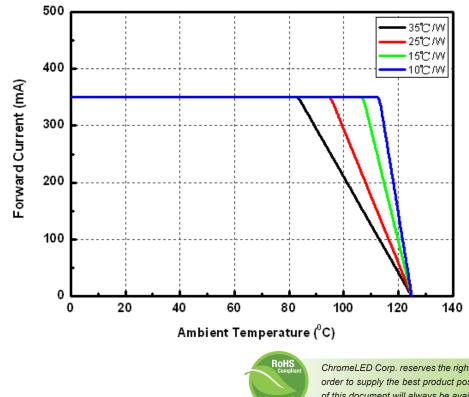


## **OPTICAL CHARACTERISTIC CURVES**

## Typical Relative Luminous Flux vs. Forward Current, Tj=25°C

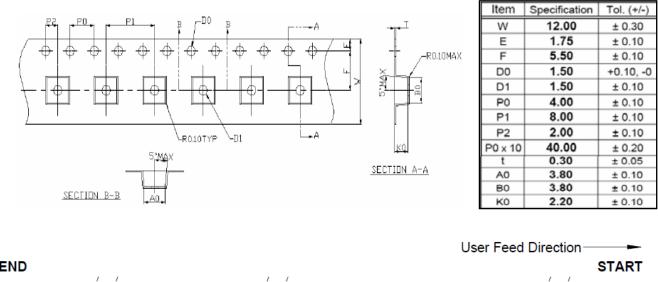


Current Derating Curve, I<sub>F</sub>=350mA





# TAPING ORIENTATION

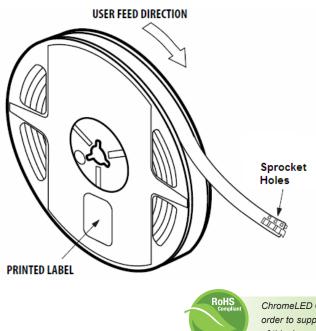


END		START

Leader 50 pockets (min) of empty pockets sealed with

Loaded Pockets (1,000 Lamps)

Trailer 20 pockets (min) of empty pockets sealed with



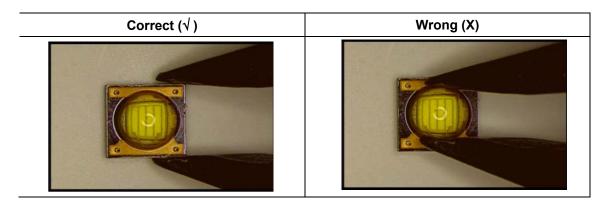


## LENS HANDLING

#### Lens handling

Please follow the guideline to grab LEDs

- Use tweezers to grab LEDs
- Do not touch lens with the tweezers
- Do not touch lens with fingers
- Do not apply more than 4N of lens (400g) directly onto the lens



#### Lens cleaning

In the case where a minimal level of dirt and dust particles can not be guaranteed, a suitable cleaning solution can be applied to the lens surface

- Try a gentle swabbing using a lint-free swab
- If needed, the use of lint-free swab and isopropyl alcohol used gently removes dirt from the lens surface
- Do not use other solvents as they may directly react with the LED assembly
- Do not use ultrasonic cleaning that the LED will be damaged
- •

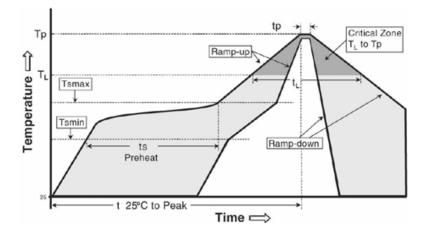






## SOLDERING CONDITIONS

### **Reflow soldering conditions**



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3° C/second max.	3° C/second max.
Preheat   - Temperature Min (Ts <sub>min</sub> )   - Temperature Max (Ts <sub>max</sub> )   - Time (Ts <sub>min</sub> to Ts <sub>max</sub> ) (ts)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time maintained above: - Temperature (T <sub>L</sub> ) - Time (t <sub>L</sub> )	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak Temperature (Tp)	215 °C	260 °C
Time within 5°C of actual Peak Temperature (tp) <sup>2</sup>	10-30 seconds	20-40 seconds
Ramp-down Rate	6 °C/second max.	6 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

